

ABSTRACT

Provided are a chip detaching apparatus and a chip detaching method, and more particularly, to a chip detaching apparatus and a chip detaching method for detaching a semiconductor chip attached to a tape and supplying the semiconductor chip to be mounted on a package or a substrate.

According to the chip detaching apparatus and the chip detaching method as described above, the semiconductor chip attached to the tape may be effectively detached while preventing damage to the semiconductor chip.